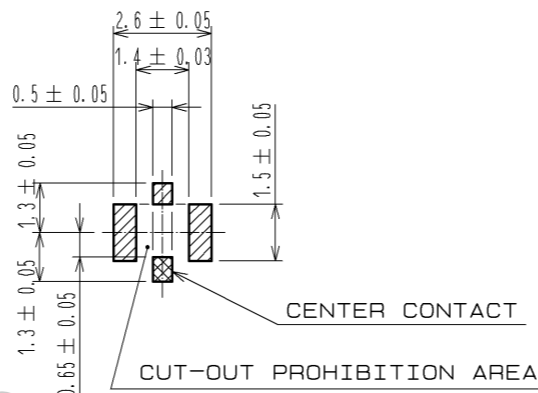
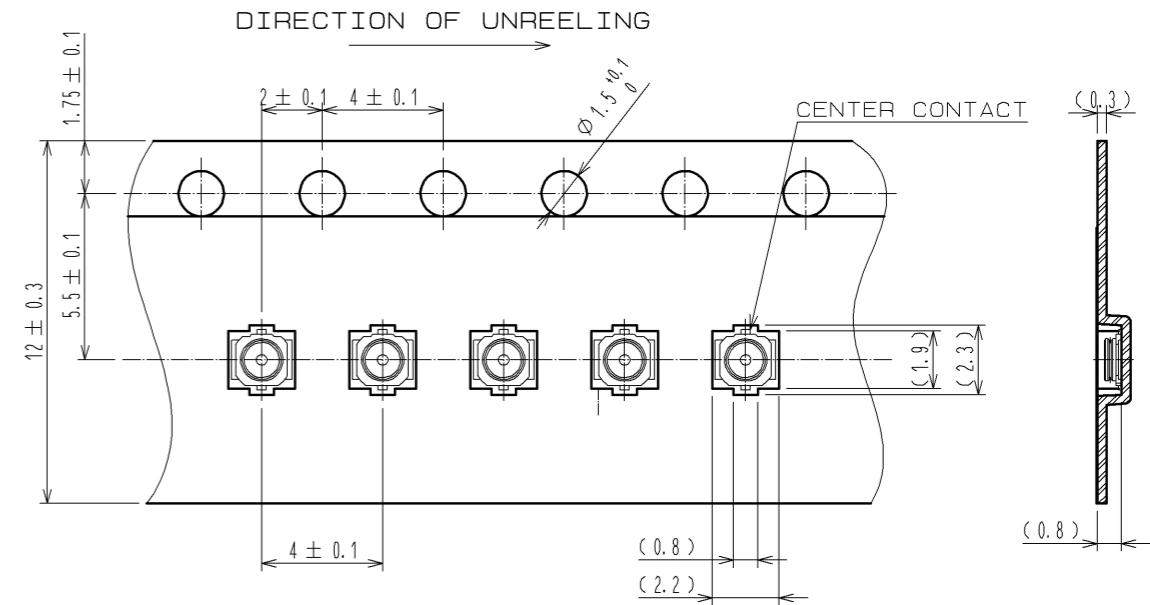


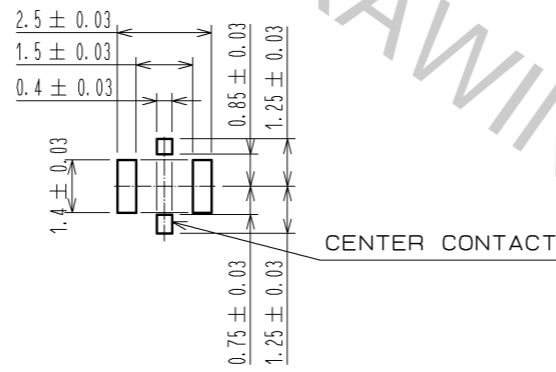
RECOMMENDED PCB LAYOUT (MOUNTING SURFACE SIDE)(5:1)



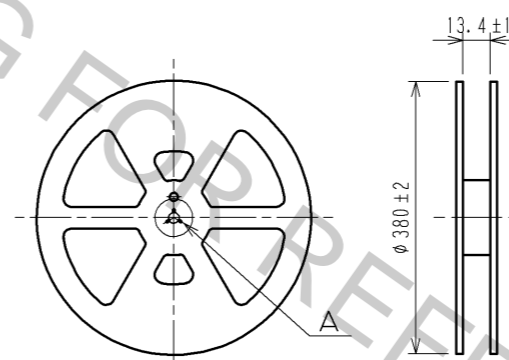
EMBOSSED TAPING DRAWING (4:1)



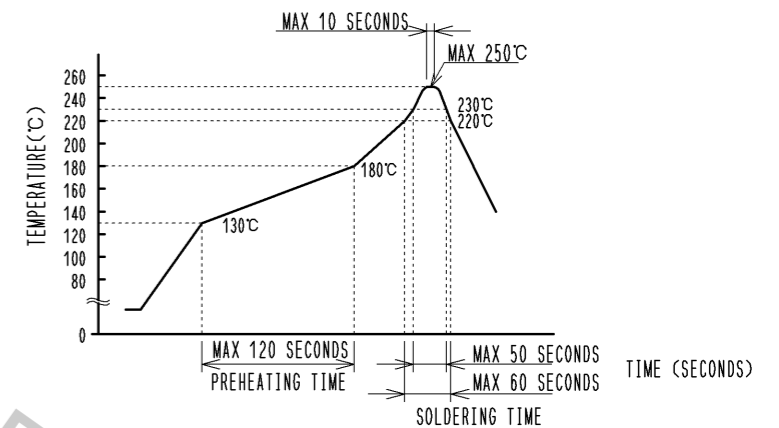
RECOMMENDED METAL MASK DIMENSIONS (5:1)
METAL MASK THICKNESS: 0.1mm/0.12mm



REEL DRAWING (SCALE FREE)



REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NOTES:

- 1: THE QUANTITY OF X.FL-R-SMT-1(90) IS 20000 CONNECTORS PER REEL.
- 2: THIS DIMENSION SHOWS THE ALLOWABLE RANGE THAT THE RESIN IS PUT OVER THE CENTER CONTACT.
- 3: LEAD CO-PLANARITY SHALL BE 0.08MAX.
- 4: FOR THE POSSIBILITY OF BREAKAGE OR DEFORMATION DO NOT MATE THIS CONNECTOR WITH PARTNER, X.FL PLUG BEFORE MOUNTING ON PC BOARD.
- 5: USE ALL PRODUCTS WITHIN 6 MONTHS AFTER THE DELIVERY. STORE THEM IN MANUFACTURER'S PACKAGE OR TIGHTLY RE-CLOSED BOX WITH THE FOLLOWING CONDITIONS. CHECK THE TERMINAL SOLDERABILITY BEFORE USE IF THE PRODUCT HAS BEEN STORED FOR MORE THAN 6 MONTHS.
TEMPERATURE: -10°C TO +40°C
HUMIDITY : 15 TO 85% RH.
- 6: ENVIRONMENTAL CONDITIONS DO NOT USE THE PRODUCTS UNDER THE ENVIRONMENTAL CONDITIONS AS SHOWN BELOW DUE TO POSSIBLE PRODUCT DETERIORATION.
SPECIAL GAS ATMOSPHERE (HYDROGEN SULFIDE GAS, SULFUR SULFIDE GAS AND HYDROGEN CHLORIDE GAS)
PLACE ATTENTION REQUIRED: HEATING SYSTEM, AREA NEAR HOT SPRING, VOLCANIC MOUNTAIN AND ALIKE.
WATER SPLACHED AND CONDENSATION PLACES.
PLACE ATTENTION REQUIRED: HARSH TEMPERATURE CHANGE.

- 1) REFLOW TIME
REFLOW METHOD : IR REFLOW
NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
DURATION ABOVE 220 °C : 60 SEC. MAX.
DURATION ABOVE 230 °C : 50 SEC. MAX.
(PEAK TEMPERATURE : 250°C 10 SEC. MAX.)
- 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN) : 130 °C
PRE-HEAT TEMPERATURE(MAX) : 180 °C
PRE-HEAT TIME: 120 SEC. MAX.

THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

RoHS COMPLIANT

1	PHOSPHOR BRONZE	UNDER PLATING: NICKEL 1.27 μm MIN CONTACT AREA PLATING: GOLD 0.03 μm MIN MOUNTING AREA PLATING: GOLD 0.03 μm MIN (SELECTIVE GOLD PLATING)	2	BRASS	UNDER PLATING: NICKEL 1.27 μm MIN CONTACT AREA PLATING: GOLD 0.1 μm MIN MOUNTING AREA PLATING: GOLD 0.03 μm MIN
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 10:1	COUNT		DESCRIPTION OF REVISIONS
APPROVED : TS. NOBE		13.11.21		DRAWING NO. EDC3-318791-90	
CHECED : NK. NINOMIYA		13.11.21		PART NO. X.FL-R-SMT-1(90)	
DESIGNED : YI. FUNADA		13.11.19		CODE NO. CL331-0701-8-90	
DRAWN : YI. FUNADA		13.11.19			